Overlay[™] Plus - Low-profile System

PRODUCT INFORMATION

Polypipe's patented Overlay[™] Plus underfloor heating board is a low-profile system that has been designed to be installed over existing floors. Making it the ideal product for renovation and new build projects.

The new Overlay[™] Plus accommodates all types of floor coverings whilst remaining lightweight rigid and easy to install.

The panels are formed of extruded polystyrene giving them their lightweight feature while also providing additional properties such as; thermal insulation, decoupling and waterproofing. The panel features two thin layers of fibre-reinforced polymer concrete with a polyester fleece-coated layer on top of an reflective aluminium foil.

The aluminium layer is designed to evenly diffuse the heat from the pipes over the surface of the board. A version to reduce transmission of impact noise is available with a layer of synthetic rubber on the bottom side.

Overlay™ Plus Floor Panel	Pack Qty.	Code No.
1200mm (L) x 600mm (W) x 18mm (D) Overlay™ Plus Panel Pack	10	UFHOP10
1200mm (L) x 600mm (W) x 18mm (D) Overlay™ Plus Panel Pack	50	UFHOP50

Overlay™ Plus Acoustic Floor Panel	Pack Qty.	Code No.
1200mm (L) x 600mm (W) x 18mm (D) Overlay™ Plus Acoustic Panel Pack	5	UFHOPA5
1200mm (L) x 600mm (W) x 18mm (D) Overlay™ Plus Acoustic Panel Pack	50	UFHOPA50



Data Sheet

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